

SN54145, SN54LS145, SN74145, SN74LS145 BCD-TO-DECIMAL DECODERS/DRIVERS

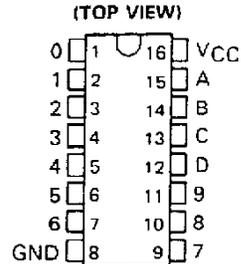
SDLS051

MARCH 1974 — REVISED MARCH 1988

FOR USE AS LAMP, RELAY, OR MOS DRIVERS

- Full Decoding of Input Logic
- SN54145, SN74145, and SN74LS145 Have 80-mA Sink-Current Capability
- All Outputs Are Off for Invalid BCD Input Conditions
- Low Power Dissipation of 'LS145 . . . 35 mW Typical

SN54145, SN54LS145 . . . J OR W PACKAGE
SN74145 . . . N PACKAGE
SN74LS145 . . . D OR N PACKAGE



FUNCTION TABLE

NO.	INPUTS				OUTPUTS										
	D	C	B	A	0	1	2	3	4	5	6	7	8	9	
0	L	L	L	L	L	H	H	H	H	H	H	H	H	H	H
1	L	L	L	H	H	L	H	H	H	H	H	H	H	H	H
2	L	L	H	L	H	H	L	H	H	H	H	H	H	H	H
3	L	L	H	H	H	H	H	L	H	H	H	H	H	H	H
4	L	H	L	L	H	H	H	H	L	H	H	H	H	H	H
5	L	H	L	H	H	H	H	H	H	L	H	H	H	H	H
6	L	H	H	L	H	H	H	H	H	H	L	H	H	H	H
7	L	H	H	H	H	H	H	H	H	H	H	L	H	H	H
8	H	L	L	L	H	H	H	H	H	H	H	H	L	H	H
9	H	L	L	H	H	H	H	H	H	H	H	H	H	H	L
INVALID	H	L	H	L	H	H	H	H	H	H	H	H	H	H	H
	H	L	H	H	H	H	H	H	H	H	H	H	H	H	H
	H	H	L	L	H	H	H	H	H	H	H	H	H	H	H
	H	H	L	H	H	H	H	H	H	H	H	H	H	H	H
	H	H	H	L	H	H	H	H	H	H	H	H	H	H	H

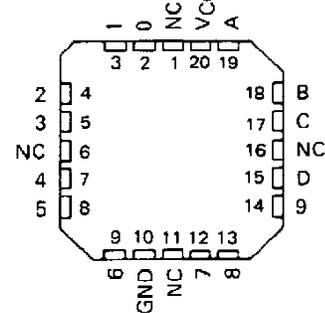
H = high level (off), L = low level (on)

description

These monolithic BCD-to-decimal decoder/drivers consist of eight inverters and ten four-input NAND gates. The inverters are connected in pairs to make BCD input data available for decoding by the NAND gates. Full decoding of valid BCD input logic ensures that all outputs remain off for all invalid binary input conditions. These decoders feature high-performance, n-p-n output transistors designed for use as indicator/relay drivers or as open-collector logic-circuit drivers. Each of the high-breakdown output transistors (15 volts) of the SN54145, SN74145, or SN74LS145 will sink up to 80 milliamperes of current. Each input is one Series 54/74 or Series 54LS/74LS standard load, respectively. Inputs and outputs are entirely compatible for use with TTL or DTL logic circuits, and the outputs are compatible for interfacing with most MOS integrated circuits. Power dissipation is typically 215 milliwatts for the '145 and 35 milliwatts for the 'LS145.

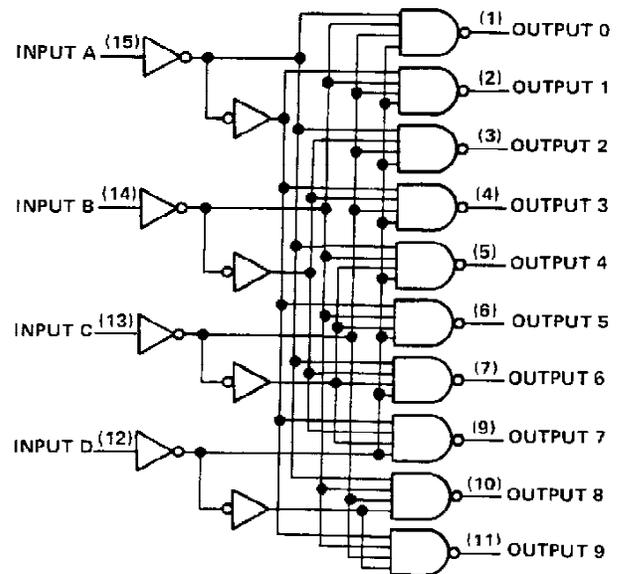
SN54LS145 . . . FK PACKAGE

(TOP VIEW)



NC : No internal connection

logic diagram



Pin numbers shown are for D, J, N, and W packages.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS

POST OFFICE BOX 855010 • DALLAS, TEXAS 75265

SN54LS145, SN74LS145 BCD-TO-DECIMAL DECODERS/DRIVERS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	5.5 V
Maximum current into any output (off-state)	1 mA
Operating free-air temperature range: SN54145	-55°C to 125°C
SN74145	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54145			SN74145			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
Off-state output voltage, $V_{O(off)}$	15			15			V
Operating free-air temperature, T_A	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
V_{IH} High-level input voltage		2			V
V_{IL} Low-level input voltage				0.8	V
V_{IK} Input clamp voltage	$V_{CC} = \text{MIN}$, $I_I = -12 \text{ mA}$			-1.5	V
$I_{O(off)}$ Off-state output current	$V_{CC} = \text{MIN}$, $V_{IH} = 2 \text{ V}$, $V_{IL} = 0.8 \text{ V}$, $V_{O(off)} = 15 \text{ V}$			250	μA
$V_{O(on)}$ On-state output voltage	$V_{CC} = \text{MIN}$, $V_{IH} = 2 \text{ V}$, $V_{IL} = 0.8 \text{ V}$		0.5	0.9	V
				0.4	
I_I Input current at maximum input voltage	$V_{CC} = \text{MAX}$, $V_I = 5.5 \text{ V}$			1	mA
I_{IH} High-level input current	$V_{CC} = \text{MAX}$, $V_I = 2.4 \text{ V}$			40	μA
I_{IL} Low-level input current	$V_{CC} = \text{MAX}$, $V_I = 0.4 \text{ V}$			-1.6	mA
I_{CC} Supply current	$V_{CC} = \text{MAX}$. See Note 2				mA
		SN54145	43	62	
		SN74145	43	70	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ \text{C}$.

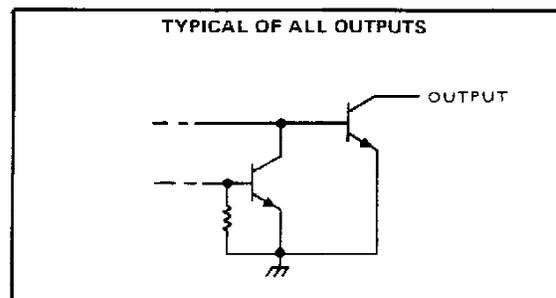
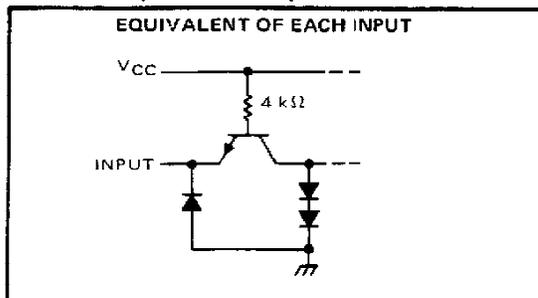
NOTE 2: I_{CC} is measured with all inputs grounded and outputs open.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ \text{C}$

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t_{PLH} Propagation delay time, low-to-high-level output	$C_L = 15 \text{ pF}$, $R_L = 100 \Omega$, See Note 3		50	ns
t_{PHL} Propagation delay time, high-to-low-level output			50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

schematics of inputs and outputs



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SN54145, SN74145 BCD-TO-DECIMAL DECODERS/DRIVERS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range: SN54LS145	-55°C to 125°C
SN74LS145	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54LS145			SN74LS145			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
Off-state output voltage, $V_{O(off)}$	15			15			V
Operating free-air temperature, T_A	-55			125			°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS145			SN74LS145			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH} High-level input voltage		2			2			V
V_{IL} Low-level input voltage		0.7			0.8			V
V_{IK} Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$	-1.5			-1.5			V
$I_{O(off)}$ Off-state output current	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}, V_{OH} = 15 \text{ V}$	250			250			μA
$V_{O(on)}$ On-state output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}$	$I_{OL} = 12 \text{ mA}$	0.25	0.4	0.25	0.4	V	
		$I_{OL} = 24 \text{ mA}$			0.35	0.5		
		$I_{OL} = 80 \text{ mA}$			2.3	3		
I_I Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$	0.1			0.1			mA
I_{IH} High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$	20			20			μA
I_{IL} Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$	-0.4			-0.4			mA
I_{CC} Supply current	$V_{CC} = \text{MAX},$ See Note 2	7	13			7	13	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ \text{C}$.

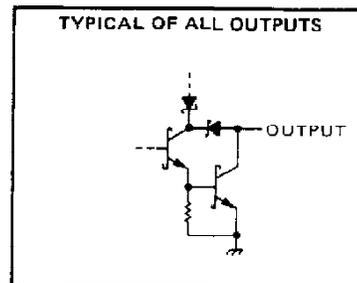
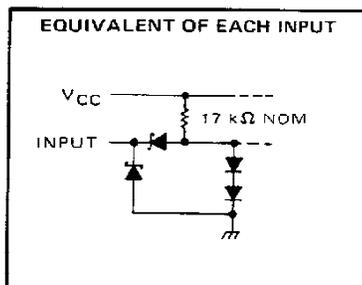
NOTE 2: I_{CC} is measured with all inputs grounded and outputs open.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ \text{C}$

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT	
t_{PLH} Propagation delay time, low-to-high-level output	$C_L = 45 \text{ pF}, R_L = 665 \Omega,$ See Note 3			50	ns
t_{PHL} Propagation delay time, high-to-low-level output				50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

schematic of inputs and outputs



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8508401VEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8508401VE A SNV54LS145J	Samples
85084012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	85084012A SNJ54LS 145FK	Samples
8508401EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8508401EA SNJ54LS145J	Samples
8508401FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8508401FA SNJ54LS145W	Samples
SN54LS145J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS145J	Samples
SN74145N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74145N	Samples
SN74LS145D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS145	Samples
SN74LS145DG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS145	Samples
SN74LS145DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS145	Samples
SN74LS145DRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS145	Samples
SN74LS145N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS145N	Samples
SN74LS145NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS145N	Samples
SN74LS145NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS145	Samples
SNJ54145J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54145J	Samples
SNJ54LS145FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	85084012A SNJ54LS 145FK	Samples
SNJ54LS145J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8508401EA SNJ54LS145J	Samples
SNJ54LS145W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8508401FA SNJ54LS145W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54145, SN54LS145, SN54LS145-SP, SN74145, SN74LS145 :

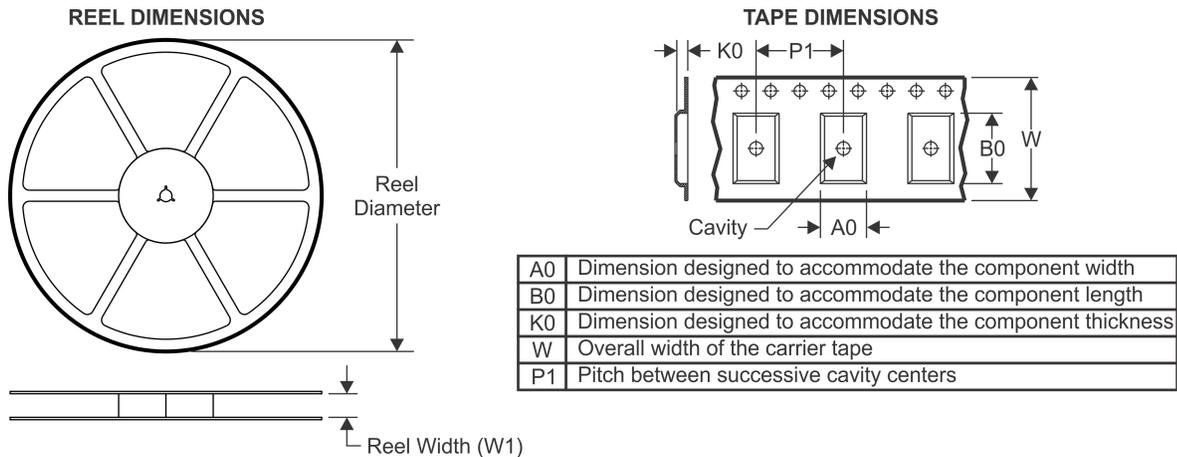
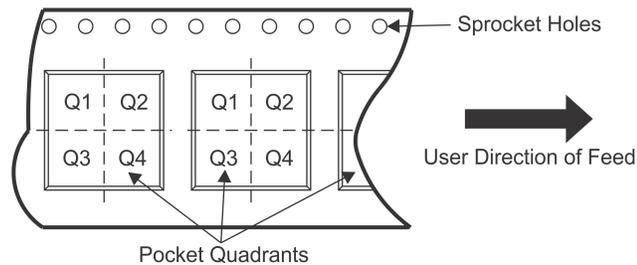
● Catalog : [SN74145](#), [SN74LS145](#), [SN54LS145](#)

● Military : [SN54145](#), [SN54LS145](#)

● Space : [SN54LS145-SP](#)

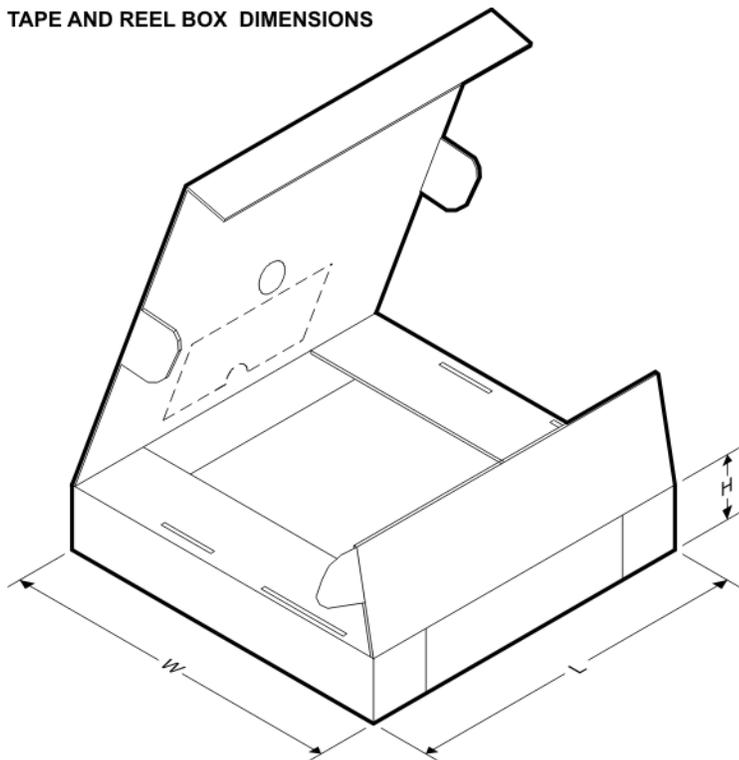
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


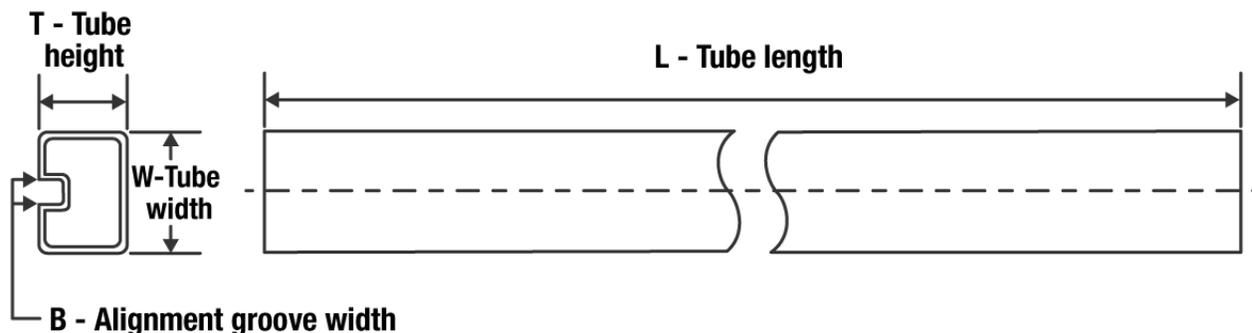
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS145DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS145NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS145DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS145NSR	SO	NS	16	2000	853.0	449.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
85084012A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74145N	N	PDIP	16	25	506	13.97	11230	4.32
SN74145N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS145D	D	SOIC	16	40	507	8	3940	4.32
SN74LS145DG4	D	SOIC	16	40	507	8	3940	4.32
SN74LS145N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS145N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS145NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS145NE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS145FK	FK	LCCC	20	1	506.98	12.06	2030	NA

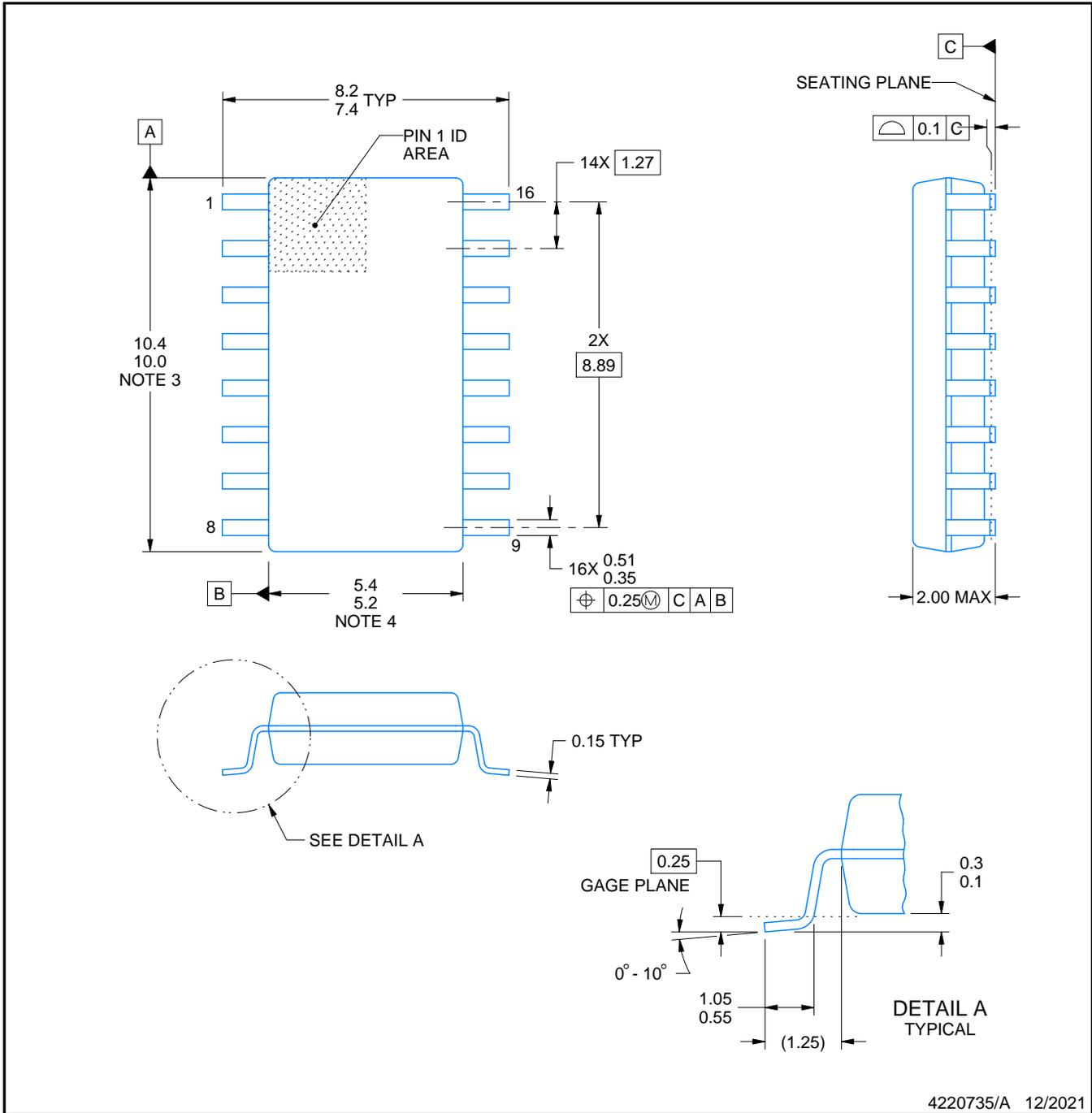


PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

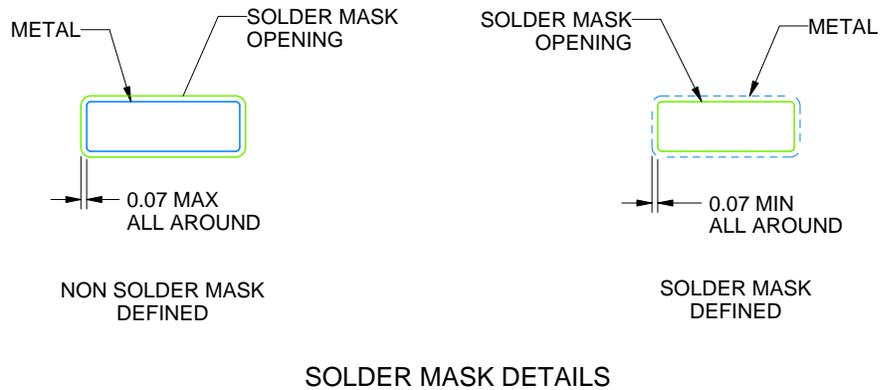
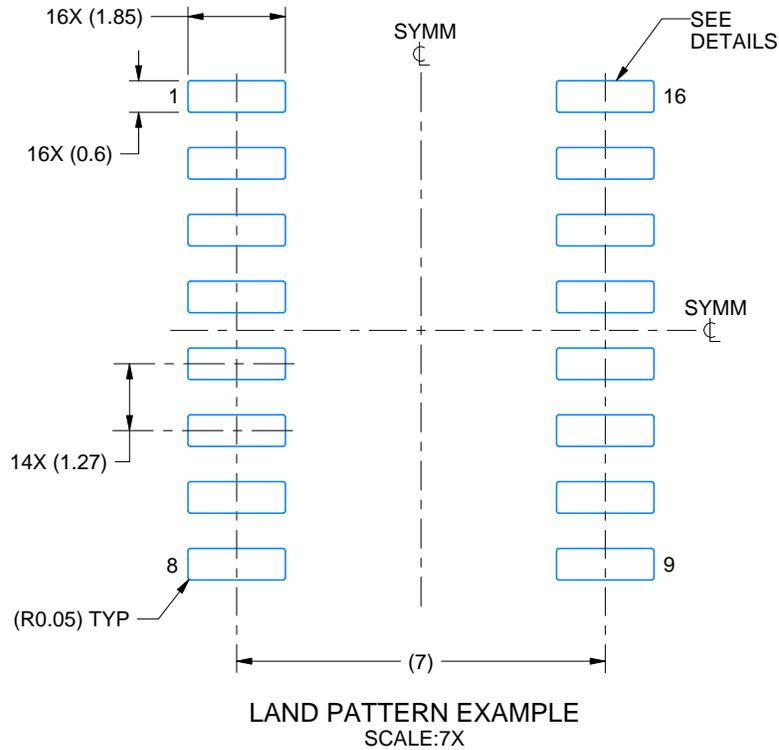
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

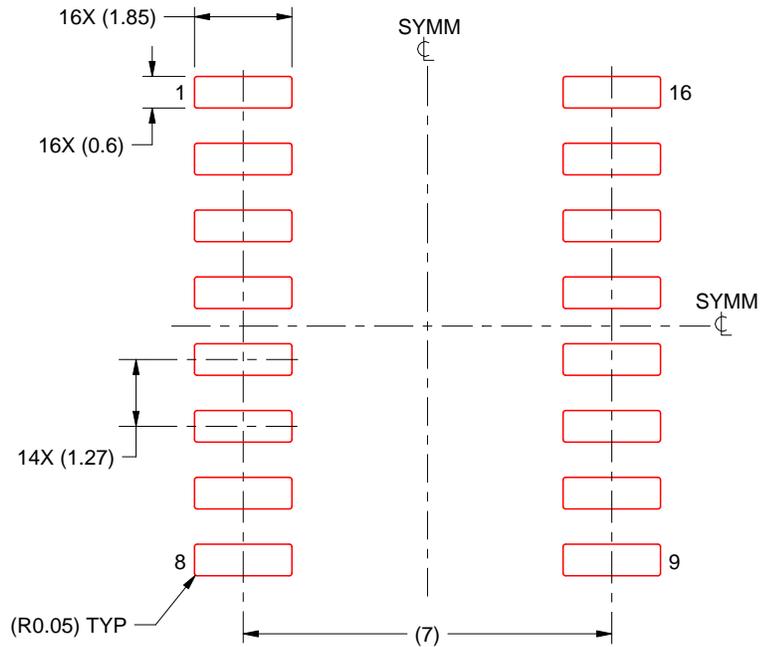
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

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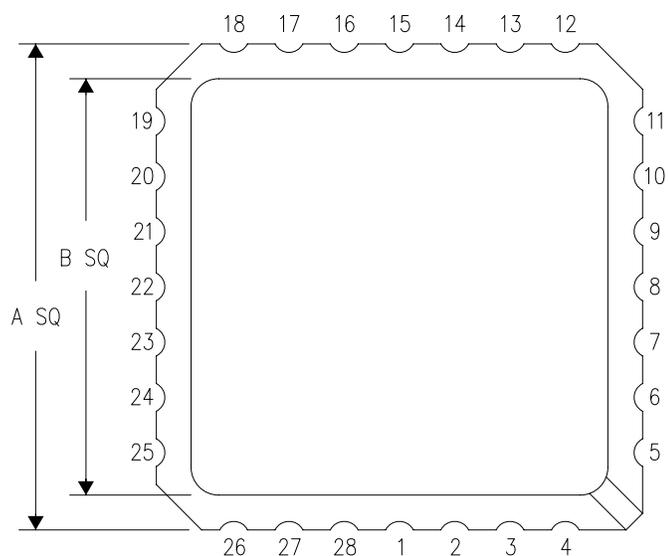
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

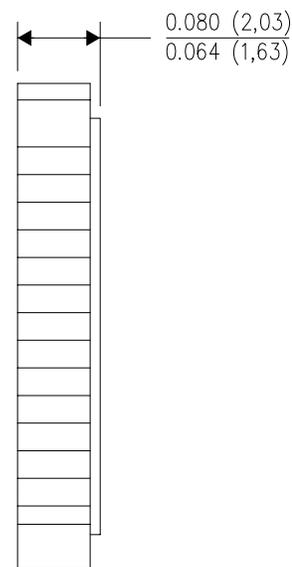
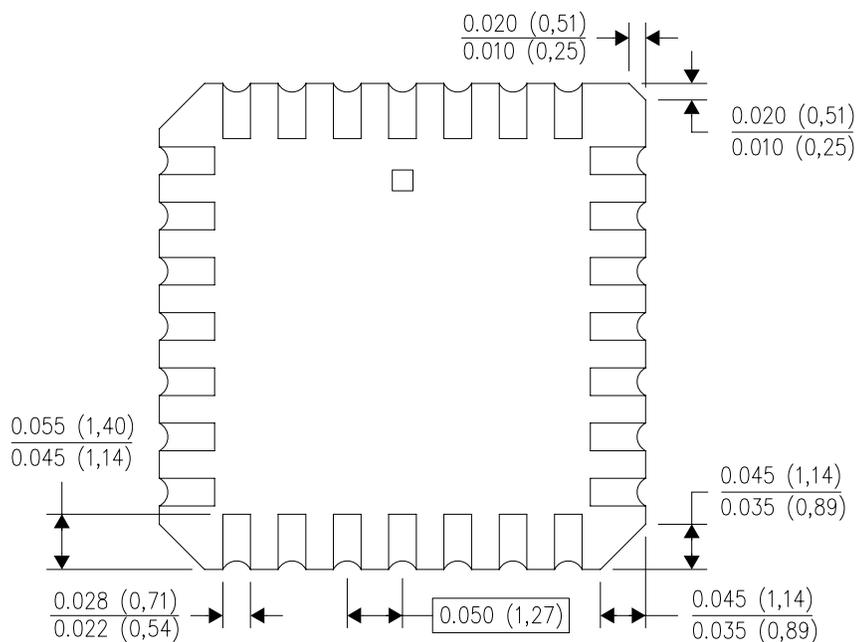
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

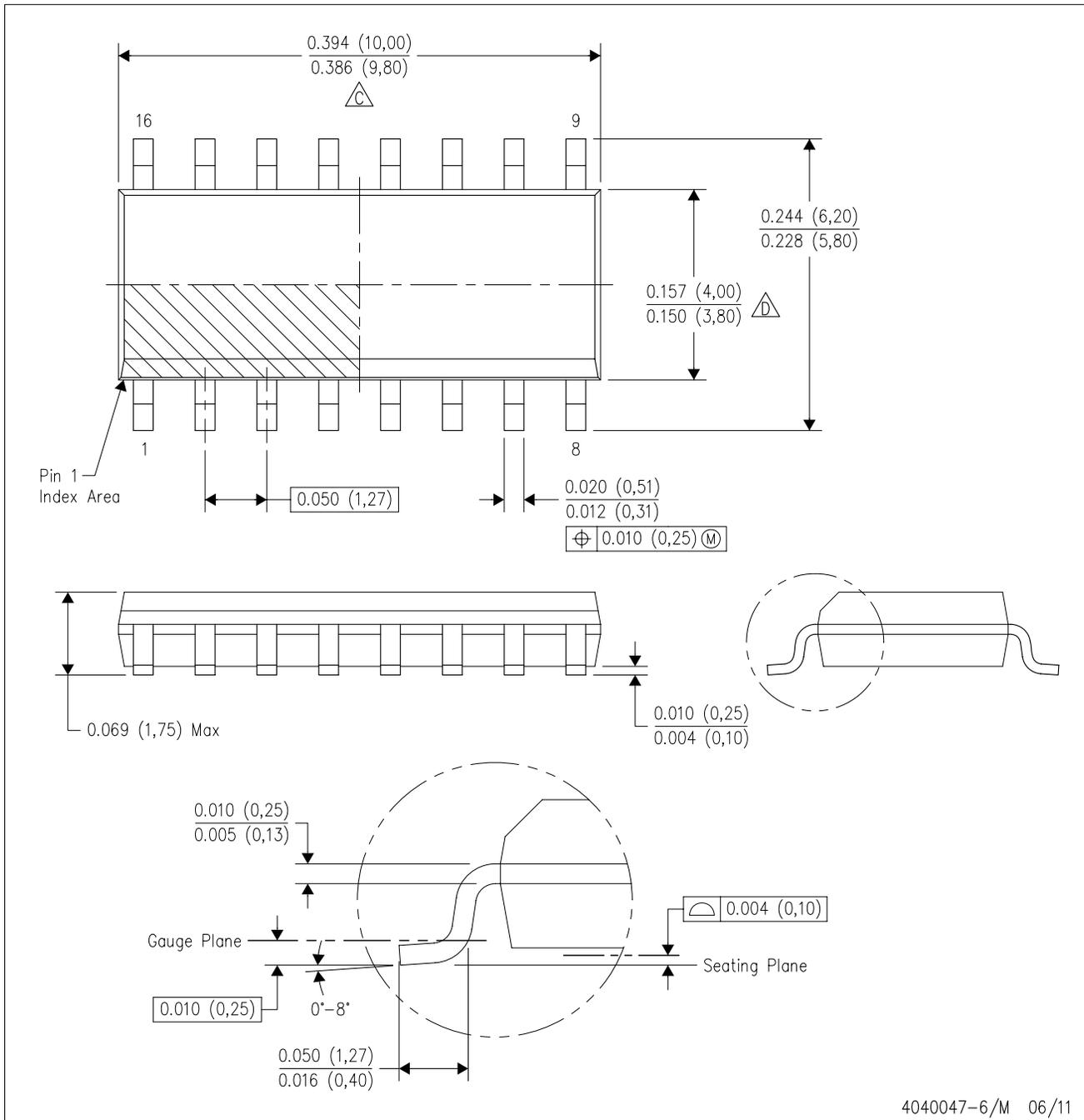


4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

D (R-PDSO-G16)

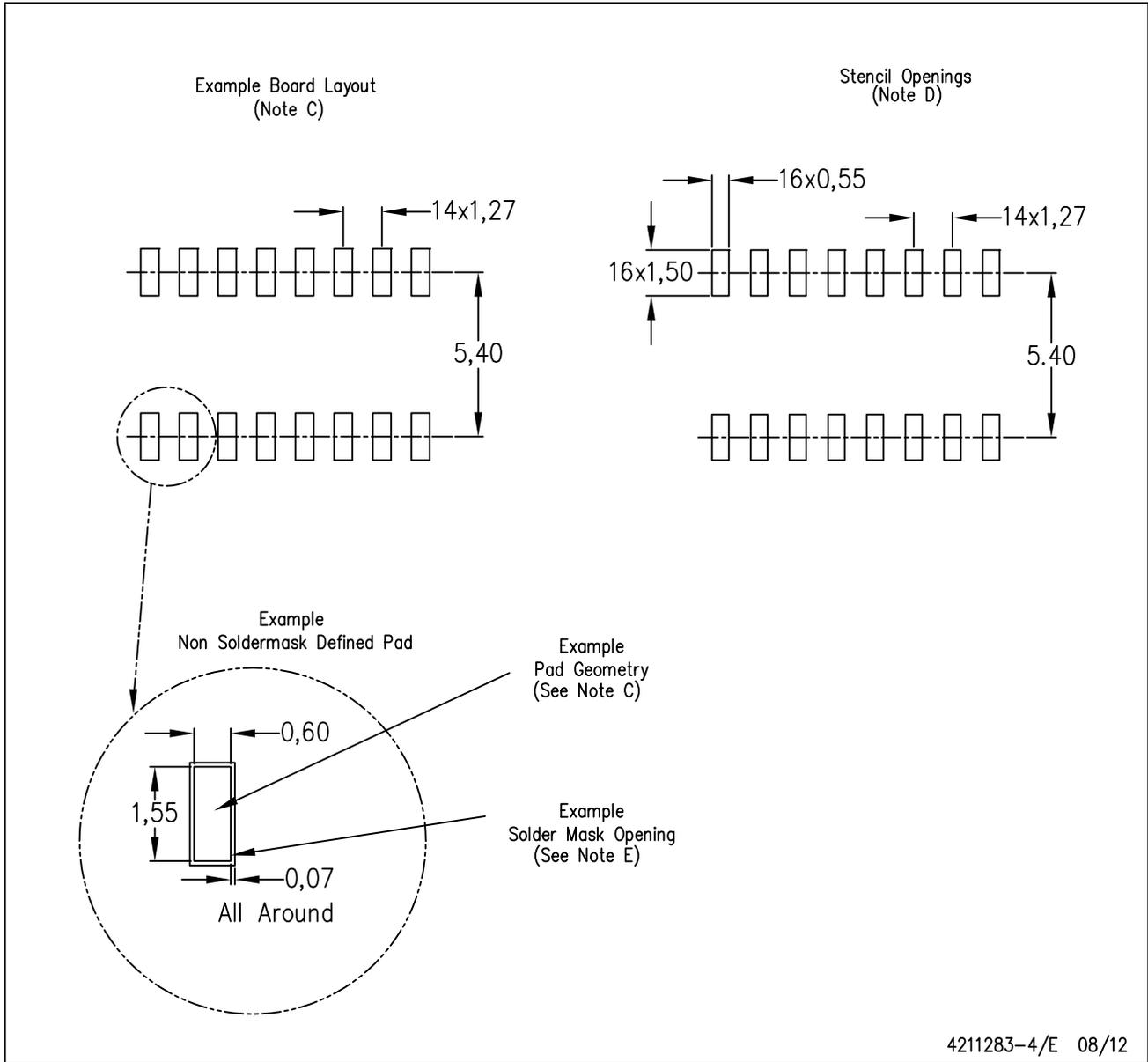
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



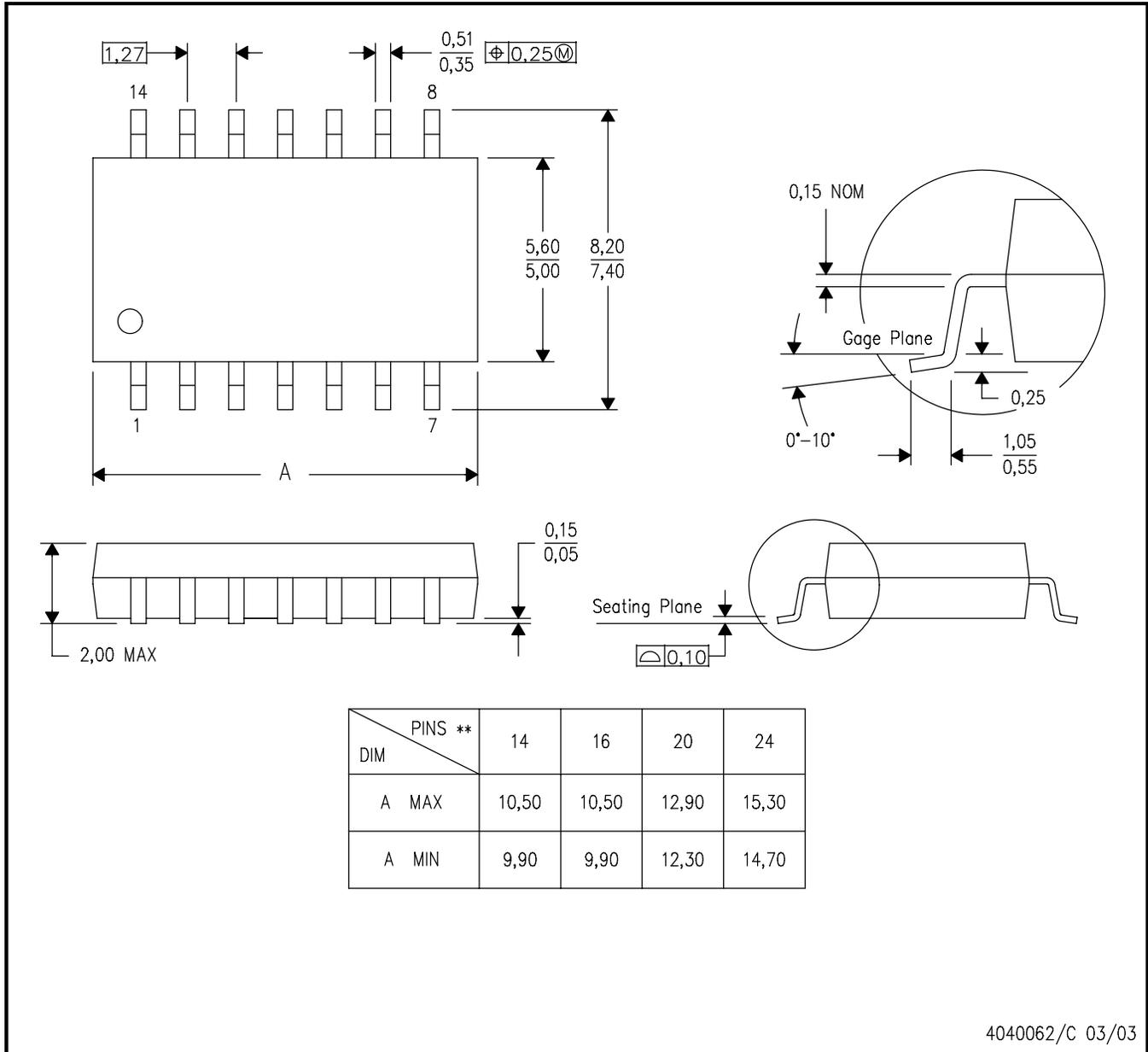
- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

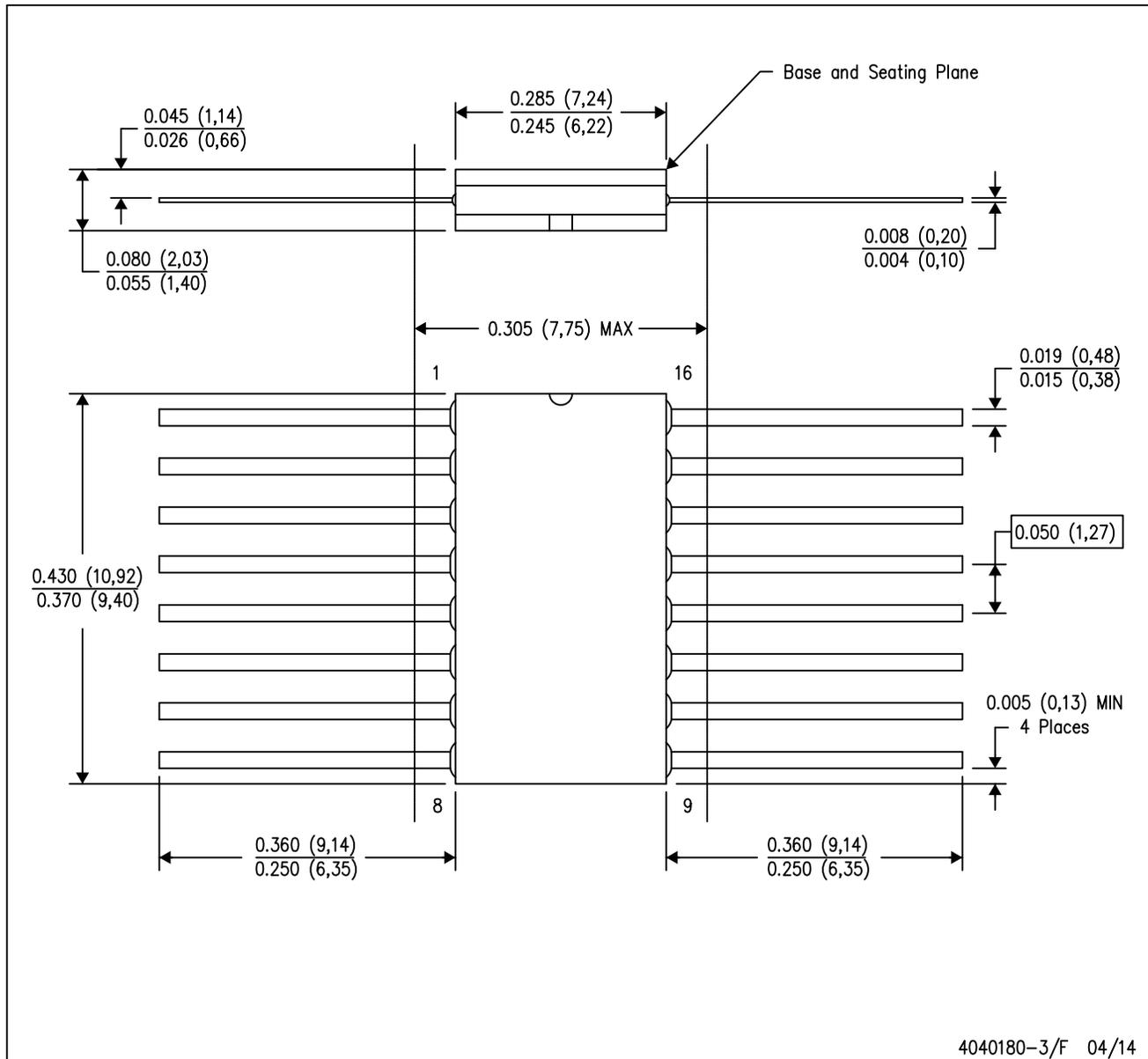
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F16)

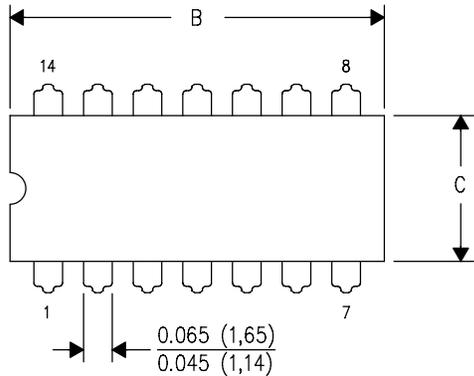
CERAMIC DUAL FLATPACK



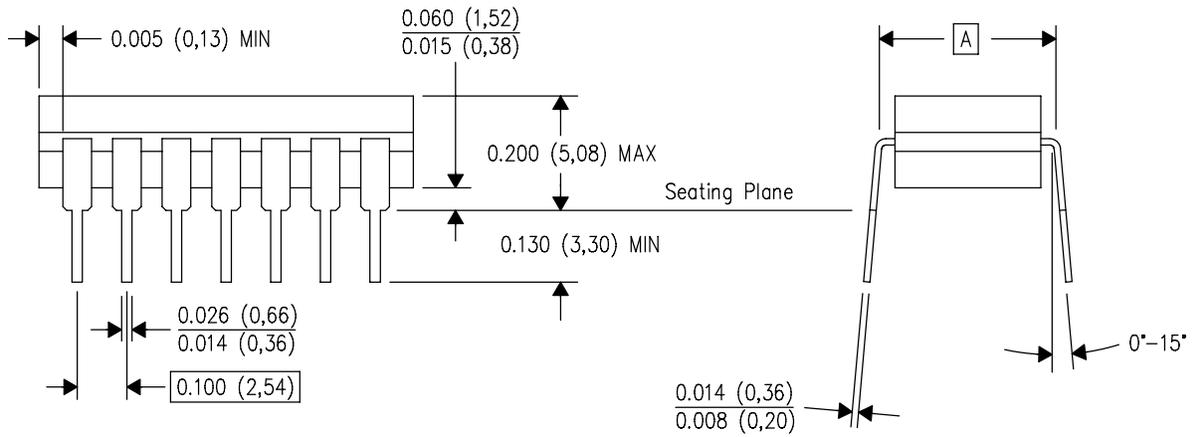
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16

J (R-GDIP-T**)
14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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